

## SCHOTTKY BARRIER RECTIFIER

### BYM99 series

#### FEATURES

- Glass passivated
- Low leakage current
- Excellent stability
- Guaranteed avalanche energy absorption capability
- Available in ammo-pack
- Also available with preformed leads for easy insertion.

#### DESCRIPTION

Rugged glass SOD64 package, using a high temperature alloyed construction.

This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.



#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{RRM}$	repetitive peak reverse voltage		–	600	V
$V_R$	continuous reverse voltage		–	600	V
$I_{F(AV)}$	average forward current	$T_{tp} = 50\text{ °C}$ ; lead length = 10 mm see Fig. 2; averaged over any 20 ms period; see also Fig 6	–	1.8	A
		$T_{amb} = 60\text{ °C}$ ; PCB mounting (see Fig.10); see Fig. 3; averaged over any 20 ms period; see also Fig. 6	–	0.8	A
$I_{FRM}$	repetitive peak forward current	$T_{tp} = 50\text{ °C}$ ; see Fig. 4	–	15	A
		$T_{amb} = 60\text{ °C}$ ; see Fig. 5	–	7	A
$I_{FSM}$	non-repetitive peak forward current	$t = 10\text{ ms}$ half sine wave; $T_j = T_{jmax}$ prior to surge; $V_R = V_{RRMmax}$	–	40	A
$E_{RSM}$	non-repetitive peak reverse avalanche energy	$L = 120\text{ mH}$ ; $T_j = T_{jmax}$ prior to surge; inductive load switched off	–	10	mJ
$T_{stg}$	storage temperature		–65	+175	°C
$T_j$	junction temperature		–65	+150	°C



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#### ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_F$	forward voltage	$I_F = 3\text{ A}; T_j = T_{j\text{ max}}; \text{ see Fig. 7}$	–	–	1.95	V
		$I_F = 3\text{ A}; \text{ see Fig. 7}$	–	–	3.60	V
$V_{(BR)R}$	reverse avalanche breakdown voltage	$I_R = 0.1\text{ mA}$	700	–	–	V
$I_R$	reverse current	$V_R = V_{RRM\text{ max}}; \text{ see Fig. 8}$	–	–	5	$\mu\text{A}$
		$V_R = V_{RRM\text{ max}}; T_j = 150\text{ °C}; \text{ see Fig. 8}$	–	–	75	$\mu\text{A}$
$t_{rr}$	reverse recovery time	when switched from $I_F = 0.5\text{ A}$ to $I_R = 1\text{ A}$ ; measured at $I_R = 0.25\text{ A}$ ; see Fig. 12	–	–	15	ns
$C_d$	diode capacitance	$f = 1\text{ MHz}; V_R = 0\text{ V}; \text{ see Fig. 9}$	–	135	–	pF
$\left  \frac{dI_R}{dt} \right $	maximum slope of reverse recovery current	when switched from $I_F = 1\text{ A}$ to $V_R \geq 30\text{ V}$ and $dI_F/dt = -1\text{ A}/\mu\text{s}$ ; see Fig.11	–	–	3	$\text{A}/\mu\text{s}$

#### THERMAL CHARACTERISTICS

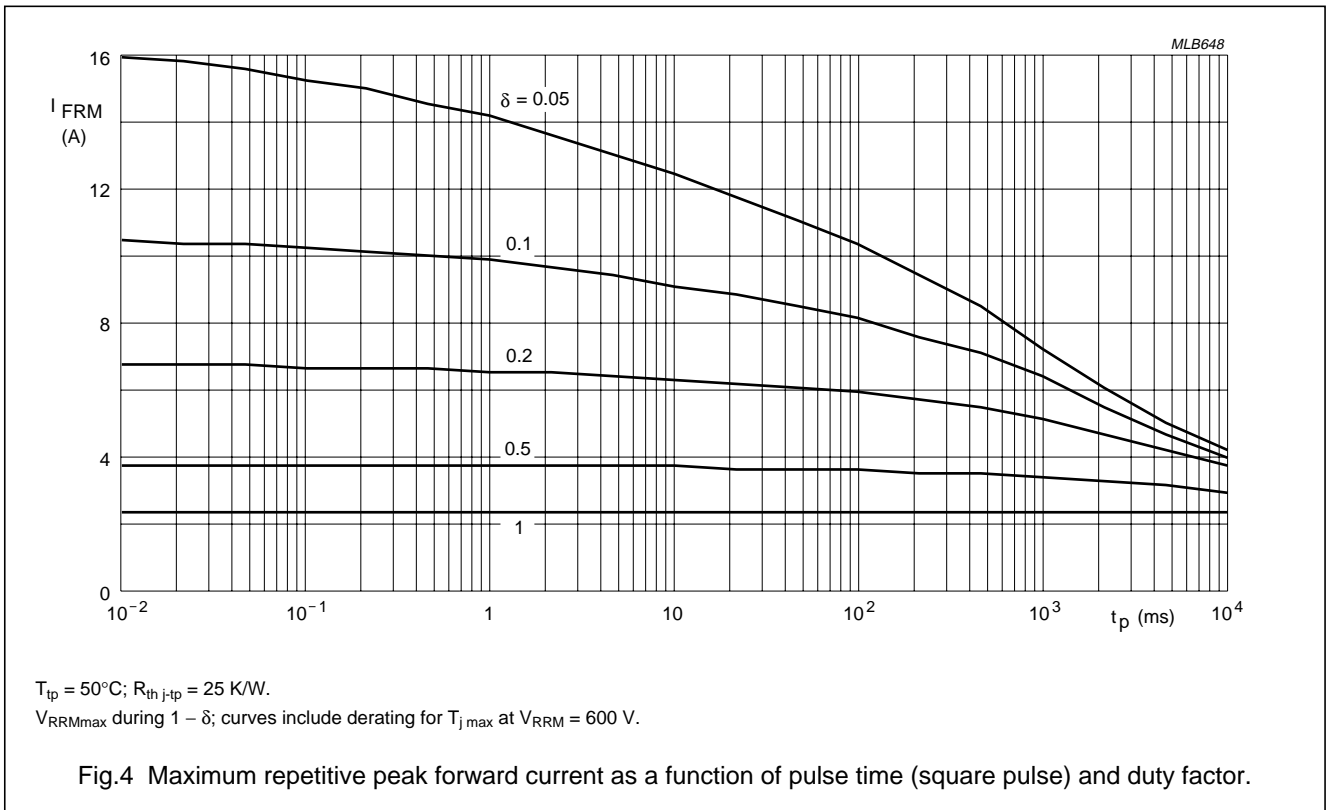
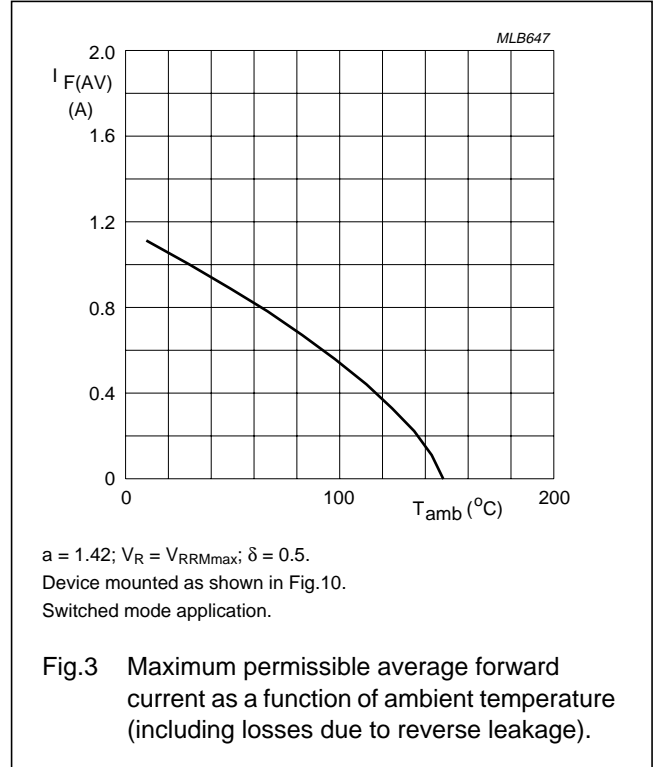
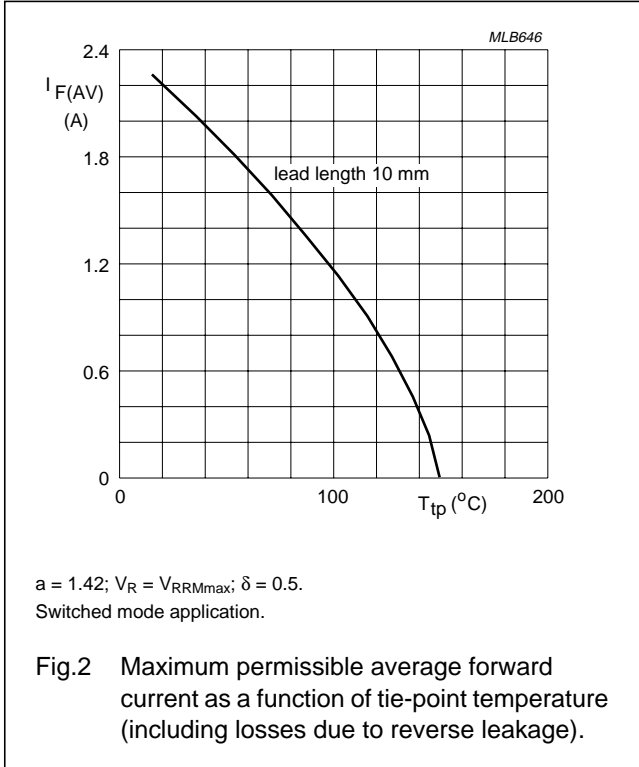
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-tp}}$	thermal resistance from junction to tie-point	lead length = 10 mm	25	K/W
$R_{th\ j\text{-a}}$	thermal resistance from junction to ambient	note 1	75	K/W

#### Note

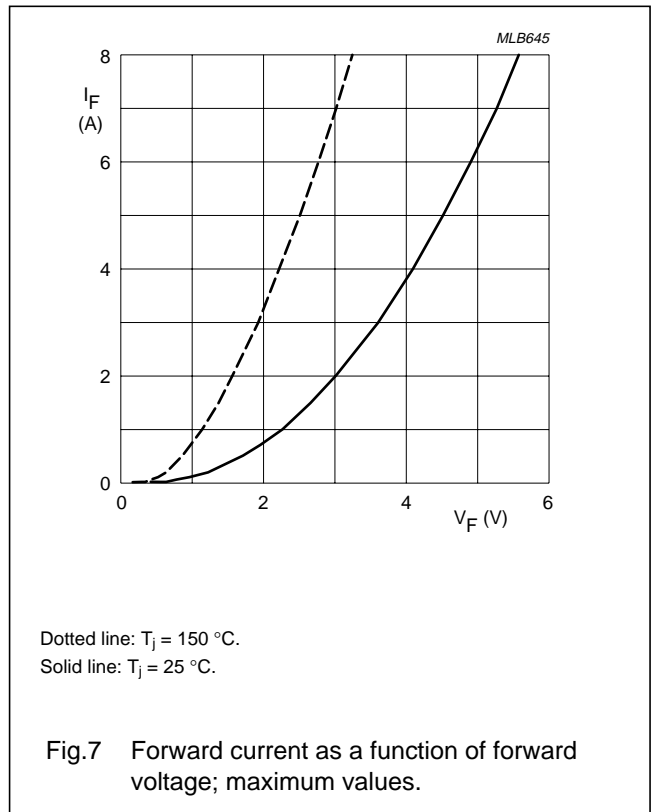
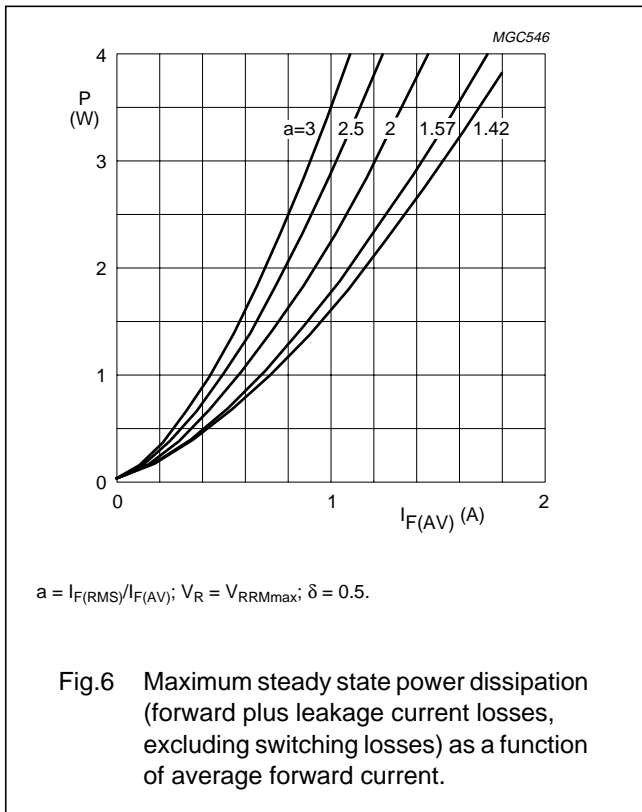
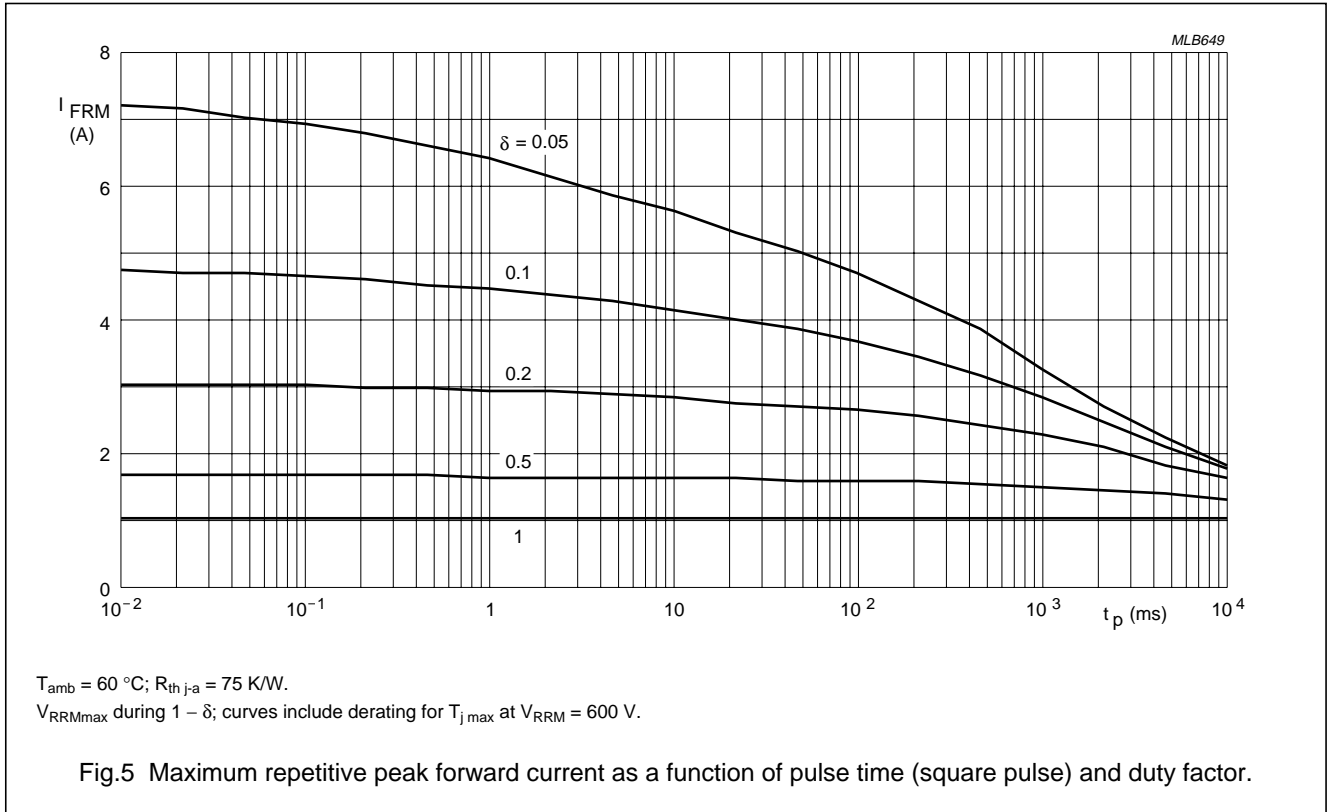
1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer  $\geq 40\text{ }\mu\text{m}$ , see Fig.10. For more information please refer to the "General Part of associated Handbook".

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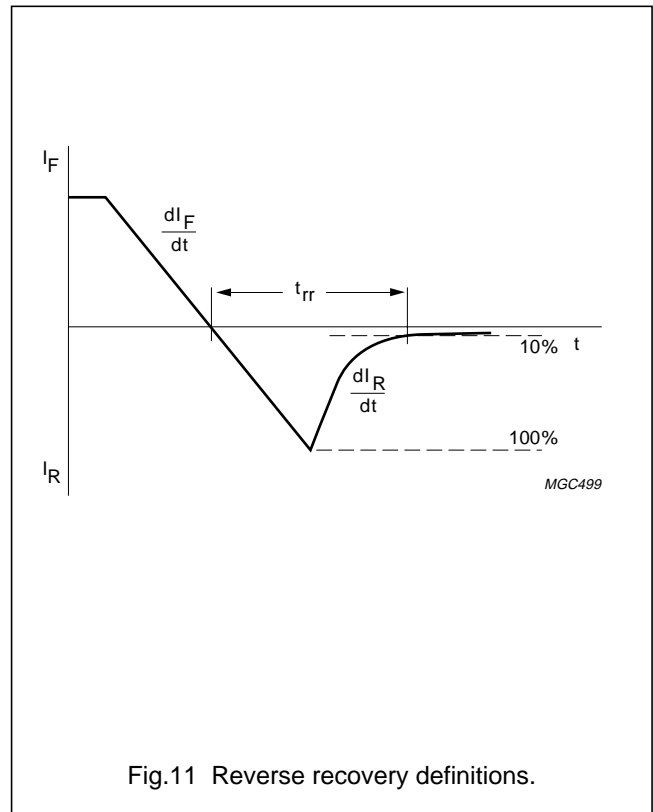
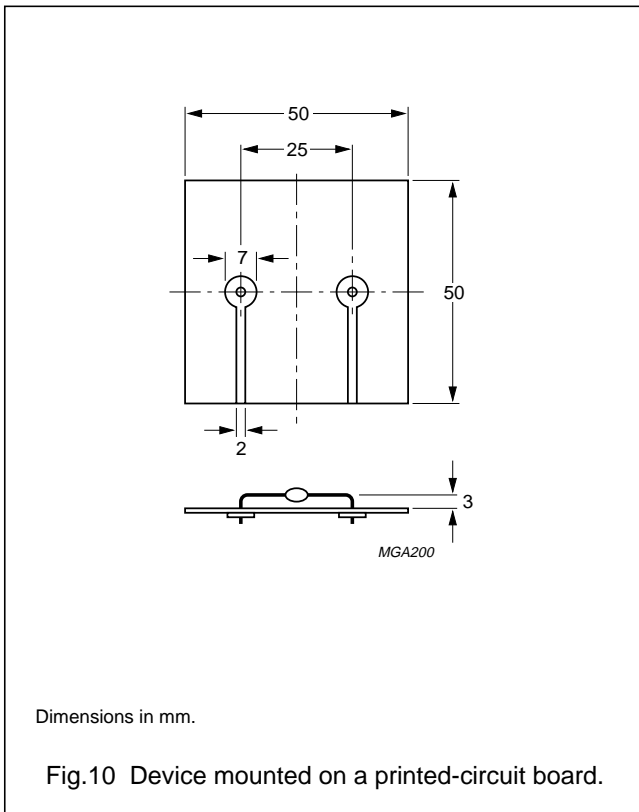
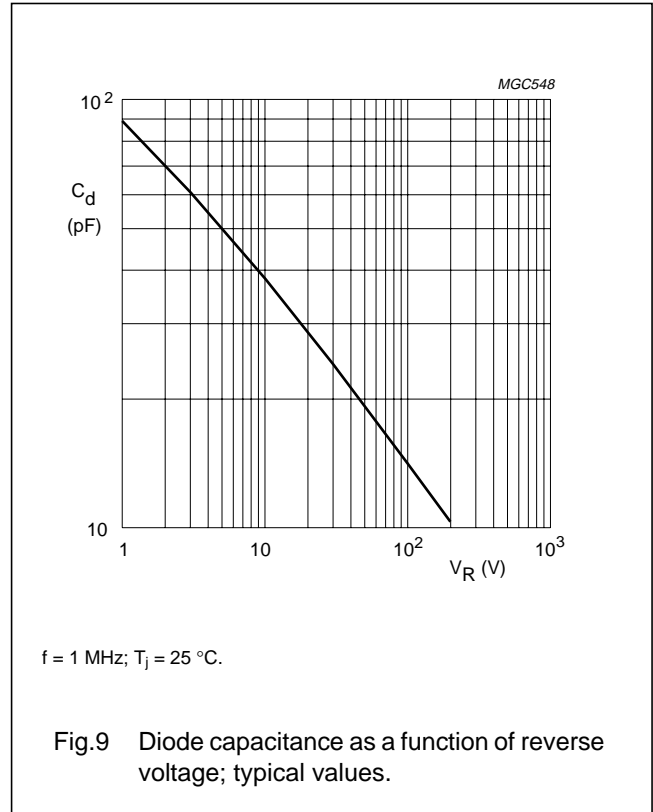
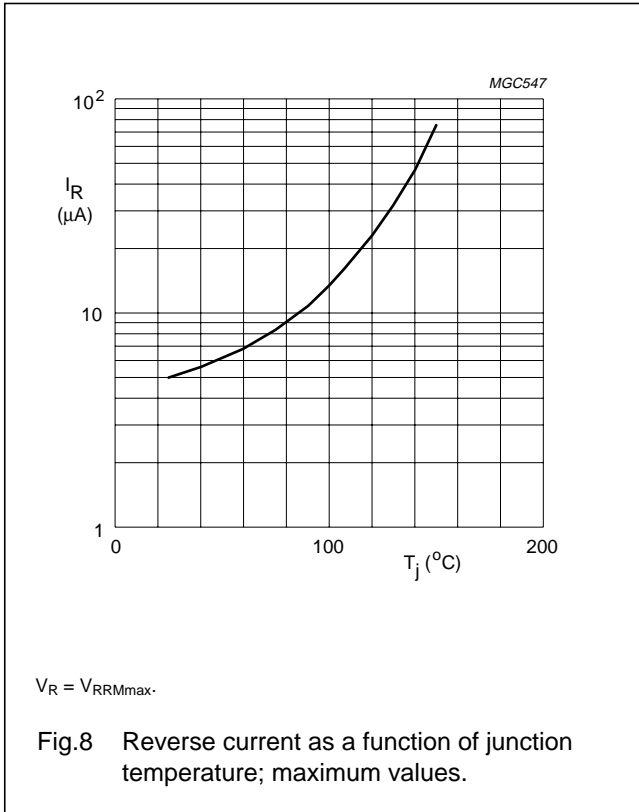
### GRAPHICAL DATA



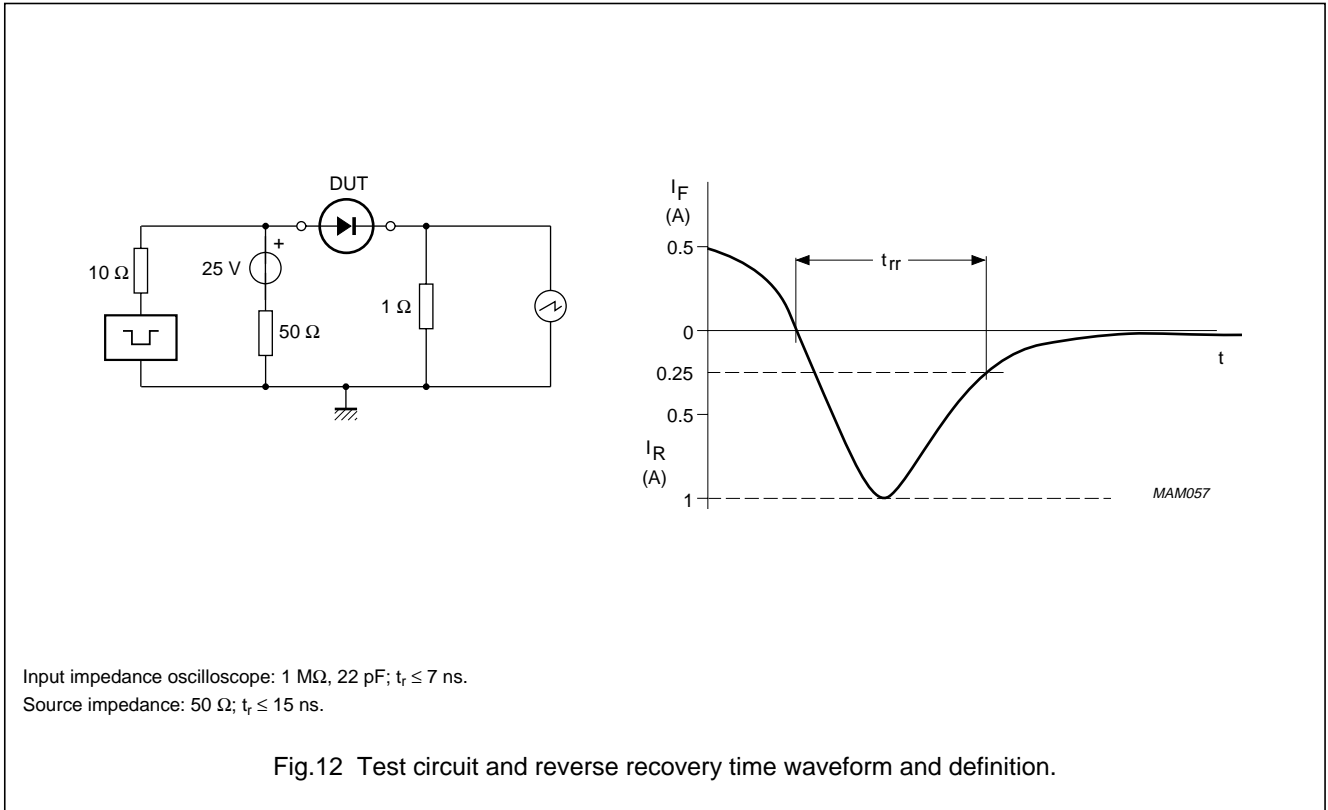
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## PACKAGE OUTLINE

